

EXHIBIT C

EXCERPT OF MAXELL, LTD.’S INTERROGATORY NO. 6

Accused Product	Model No.	Application Processor Chipset				Camera Module(s) (Primary / Front-Facing)				Image Sensor(s) (Primary / Front-Facing)			
		Internal Model No.	Supplier	Supplier Model No.	Cost Per Unit	Internal Model No.	Supplier	Supplier Model No.	Cost Per Unit	Internal Model No.	Supplier	Supplier Model No.	Cost Per Unit
iPhone XS	A1920												
iPhone XS Max	A1921												
iPhone XR	A1984												
iPhone X	A1865												
[repeats for each accused product]													

Accused Product	Model No.	Image Sensor(s) (Secondary / Rear-Facing)				Bluetooth Chipset				GPS Chipset			
		Internal Model No.	Supplier	Supplier Model No.	Cost Per Unit	Internal Model No.	Supplier	Supplier Model No.	Cost Per Unit	Internal Model No.	Supplier	Supplier Model No.	Cost Per Unit
iPhone XS	A1920												
iPhone XS Max	A1921												
iPhone XR	A1984												
iPhone X	A1865												
[repeats for each accused product]													

Other listed components: Baseband Processor Chipset, Gyroscope(s), Accelerometer, Proximity Sensor, Power Management Circuit/Processor, Antenna, RF Chipset, Compass, Image Signal Processor, Duplexer, Power Amplifier, Processor/CPU.